FIG. 1

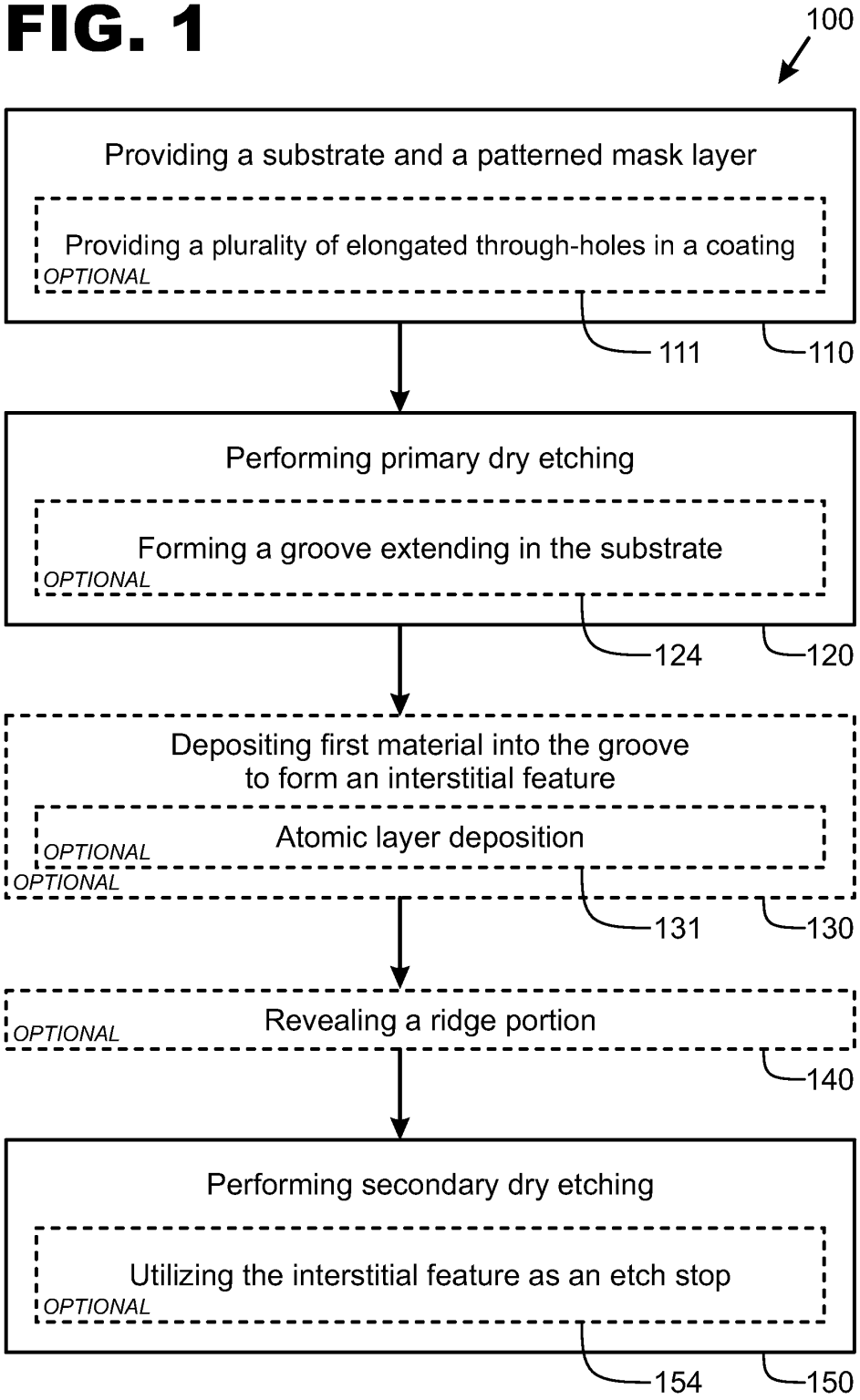

100
Providing a substrate and a patterned mask layer
Providing a plurality of elongated through-holes in a coating
OPTIONAL
111
110
Performing primary dry etching
Forming a groove extending in the substrate
OPTIONAL
124
120
Depositing first material into the groove to form an interstitial feature
Atomic layer deposition
OPTIONAL
OPTIONAL
131
130
Revealing a ridge portion
OPTIONAL
140
Performing secondary dry etching
Utilizing the interstitial feature as an etch stop
OPTIONAL
154
150

FIG. 2A

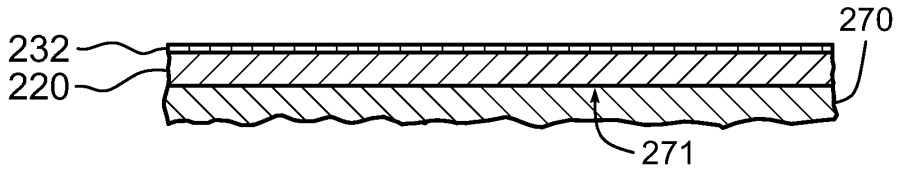


FIG. 2B

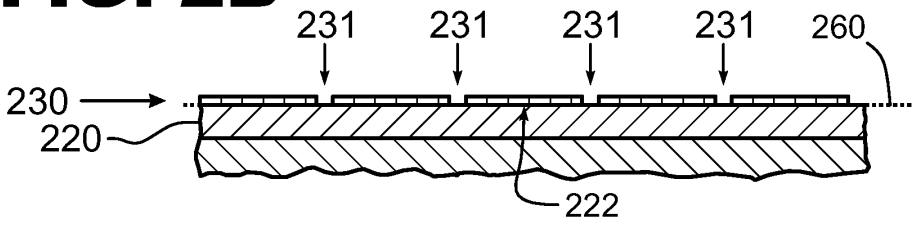


FIG. 2C

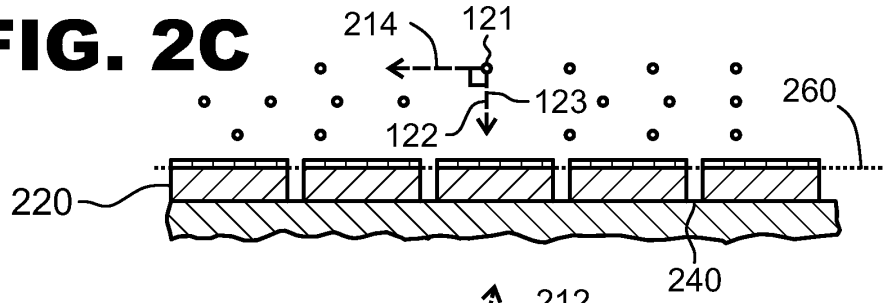


FIG. 2D

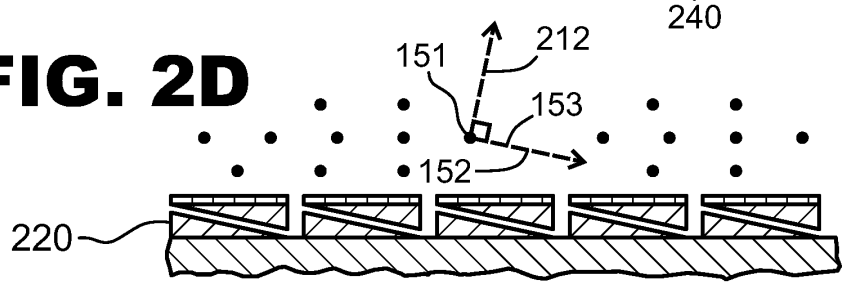


FIG. 2E

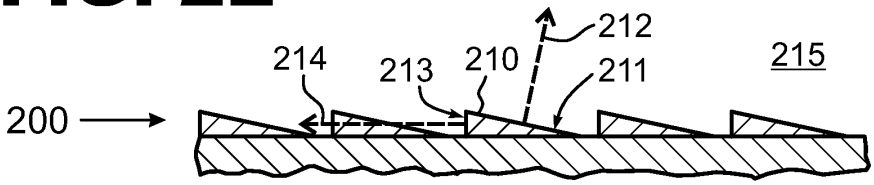


FIG. 3A

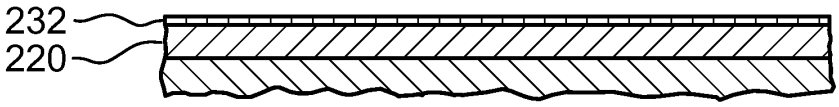


FIG. 3B

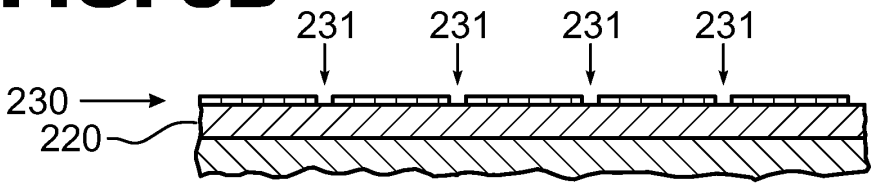


FIG. 3C

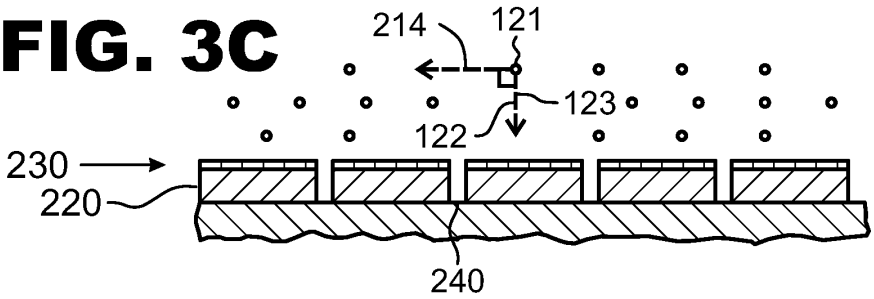


FIG. 3D

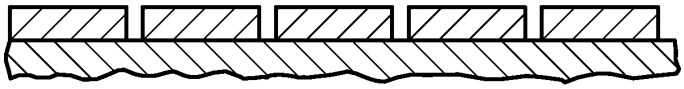


FIG. 3E

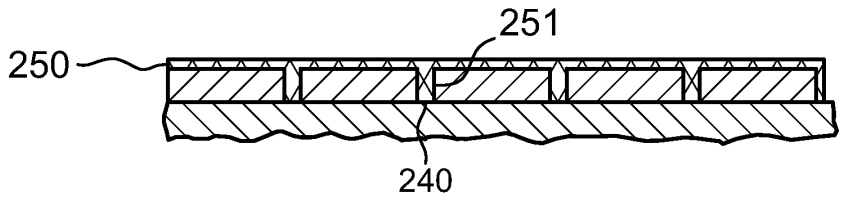


FIG. 3F

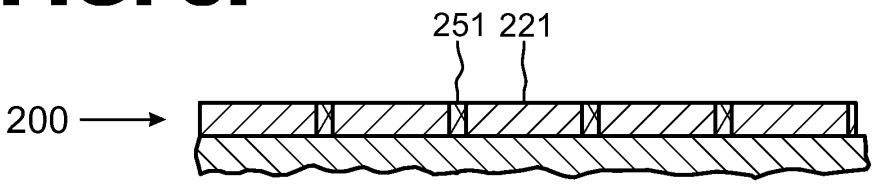


FIG. 3G

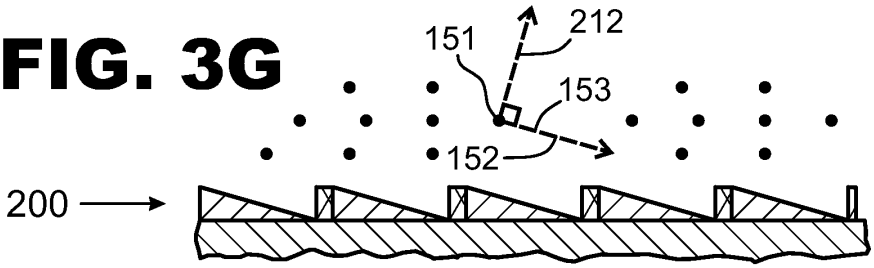


FIG. 3H

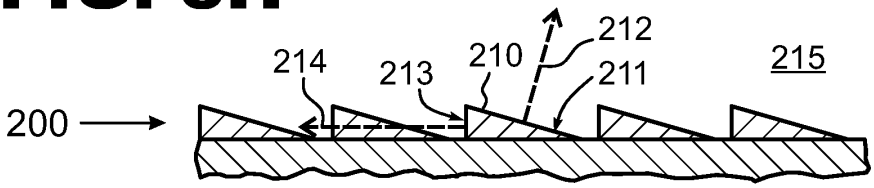


FIG. 4A

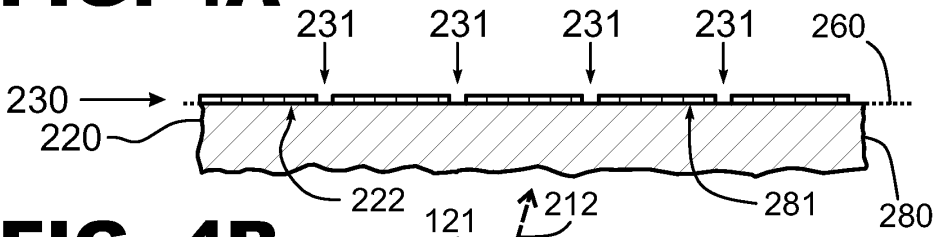


FIG. 4B

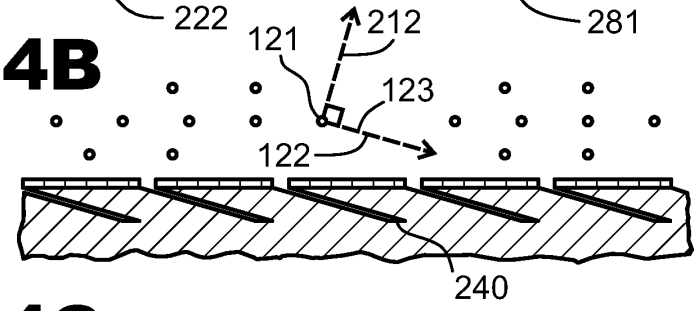


FIG. 4C

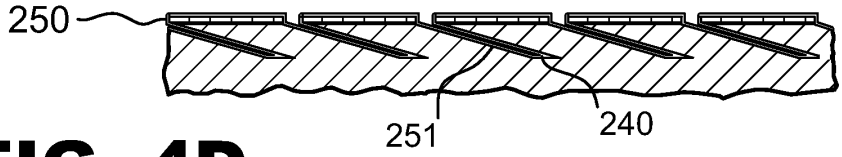


FIG. 4D

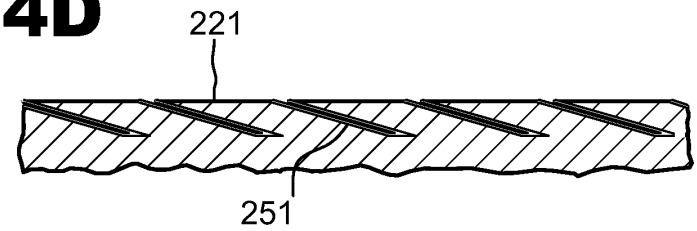


FIG. 4E

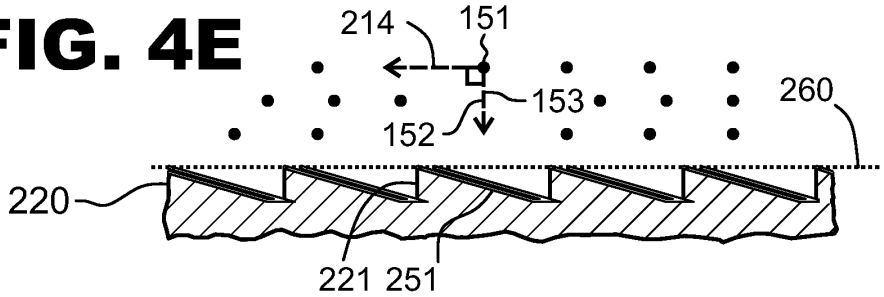


FIG. 4F

